



ESD



TVS



TSS



DIODES



IC



BJT



MOS

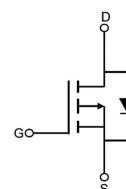
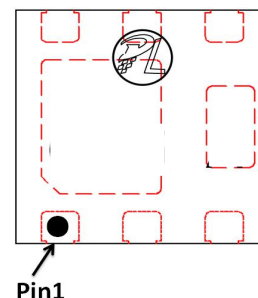
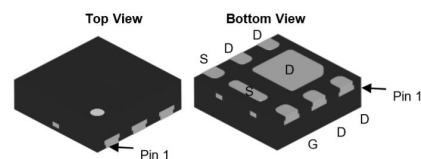


LDO

Product Specification

www.plingsemic.com

DFN2020-6L



Schematic Diagram

Features

- Advanced Trench Technology
- Excellent $R_{DS(on)}$ and Low Gate Charge
- Lead Free

Application

- PWM Applications
- Load Switch
- Power Management

Package Marking and Ordering Information

Device Marking	Device	Outline	Package	Reel Size	Reel(pcs)	Per Carton (pcs)
	PMPB13UP	TAPING	DFN2020-6L	7"	3000	120000

Absolute Maximum Ratings (@ $T_A = 25^\circ\text{C}$ unless otherwise specified)

Symbol	Parameter	Value	Units
V_{DS}	Drain-to-Source Voltage	-20	V
V_{GS}	Gate-to-Source Voltage	± 12	V
I_D	Continuous Drain Current	$T_A = 25^\circ\text{C}$	A
		$T_A = 100^\circ\text{C}$	
I_{DM}	Pulsed Drain Current ⁽¹⁾	-45	A
E_{AS}	Single Pulsed Avalanche Energy ⁽²⁾	25	mJ
P_D	Power Dissipation	$T_A = 25^\circ\text{C}$	W
$R_{\theta JA}$	Thermal Resistance, Junction to Ambient ⁽³⁾	49	$^\circ\text{C/W}$
T_J, T_{STG}	Junction & Storage Temperature Range	-55 to 150	$^\circ\text{C}$

Electrical Characteristics (T_J = 25°C unless otherwise specified)

Symbol	Parameter	Conditions	Min.	Typ.	Max.	Unit
Off Characteristics						
V _{(BR)DSS}	Drain-Source Breakdown Voltage	I _D = -250μA, V _{GS} = 0V	-20	-	-	V
I _{DSS}	Zero Gate Voltage Drain Current	V _{DS} = -20V, V _{GS} = 0V	-	-	-1.0	μA
I _{GSS}	Gate-Body Leakage Current	V _{DS} = 0V, V _{GS} = ±12V	-	-	±100	nA
On Characteristics						
V _{GS(th)}	Gate Threshold Voltage	V _{DS} = V _{GS} , I _D = -250μA	-0.4	-0.62	-1.0	V
R _{DS(ON)}	Static Drain-Source ON-Resistance ⁽⁴⁾	V _{GS} = -4.5V, I _D = -8A	-	14	19	mΩ
		V _{GS} = -2.5V, I _D = -5A	-	18	23	mΩ
Dynamic Characteristics						
C _{iss}	Input Capacitance	V _{GS} = 0V, V _{DS} = -10V, f = 1MHz	-	1332	-	pF
C _{oss}	Output Capacitance		-	184	-	pF
C _{rss}	Reverse Transfer Capacitance		-	162	-	pF
Q _g	Total Gate Charge	V _{GS} = 0 to -4.5V V _{DS} = -10V, I _D = -10A	-	16	-	nC
Q _{gs}	Gate Source Charge		-	4	-	nC
Q _{gd}	Gate Drain("Miller") Charge		-	3	-	nC
Switching Characteristics						
t _{d(on)}	Turn-On DelayTime	V _{GS} = -4.5V, V _{DD} = -10V I _D = -10A, R _{GEN} = 3Ω	-	8	-	ns
t _r	Turn-On Rise Time		-	35	-	ns
t _{d(off)}	Turn-Off DelayTime		-	71	-	ns
t _f	Turn-Off Fall Time		-	70	-	ns
Drain-Source Diode Characteristics and Max Ratings						
I _S	Maximum Continuous Drain to Source Diode Forward Current		-	-	-12	A
I _{SM}	Maximum Pulsed Drain to Source Diode Forward Current		-	-	-45	A
V _{SD}	Drain to Source Diode Forward Voltage	V _{GS} = 0V, I _S = -15A	-	-	-1.2	V
trr	Body Diode Reverse Recovery Time	I _F = -10A, di/dt = 100A/us	-	10	-	ns
Qrr	Body Diode Reverse Recovery Charge		-	3	-	nC

Notes:

1. Repetitive Rating: Pulse Width Limited by Maximum Junction Temperature.
2. EAS condition: Starting T_J=25°C, V_{DD}=-15V, V_G=-10V, R_G=250mΩ, L=0.5mH, I_{AS}=-10A
3. R_{θJA} is measured with the device mounted on a 1inch² pad of 2oz copper FR4 PCB
4. Pulse Test: Pulse Width≤300μs, Duty Cycle≤0.5%.

Typical Performance Characteristics

Figure 1: Output Characteristics

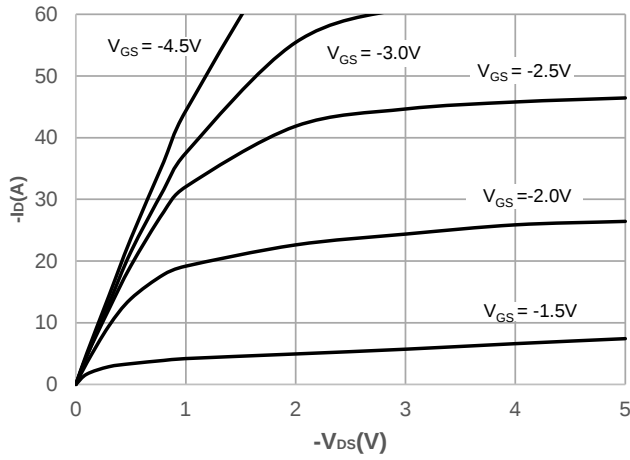


Figure 2: Typical Transfer Characteristics

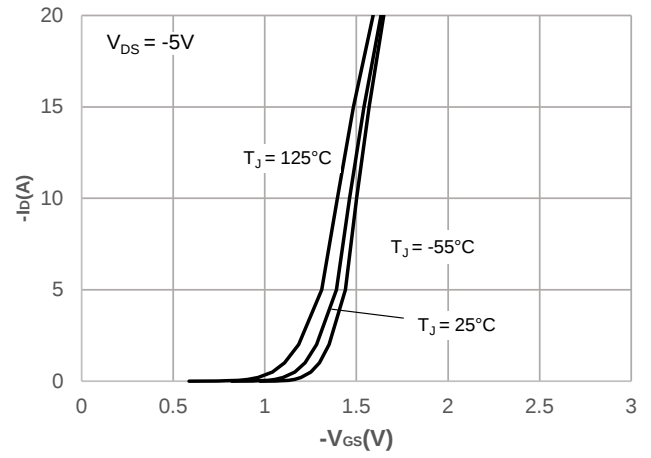


Figure 3: On-resistance vs. Drain Current

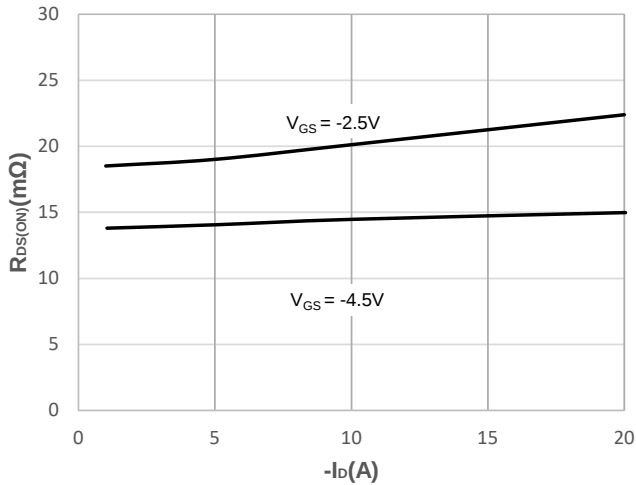


Figure 4: Body Diode Characteristics

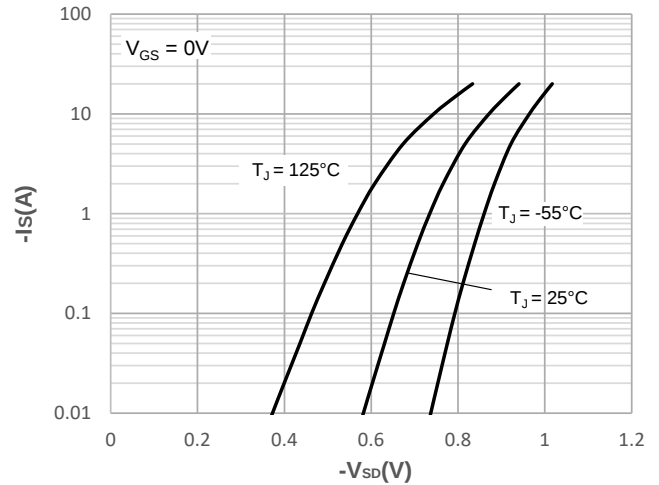


Figure 5: Gate Charge Characteristics

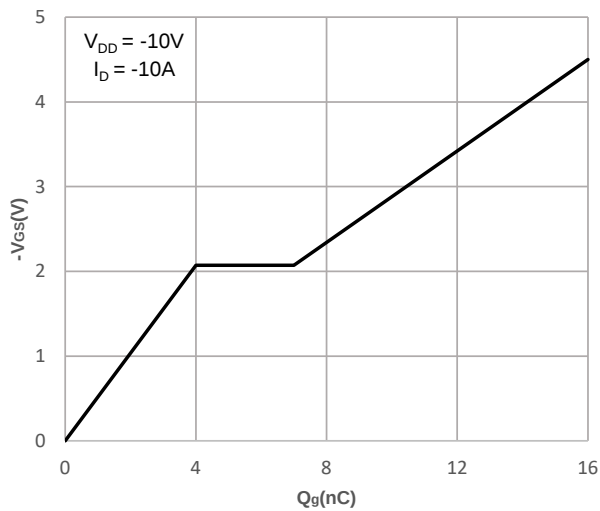
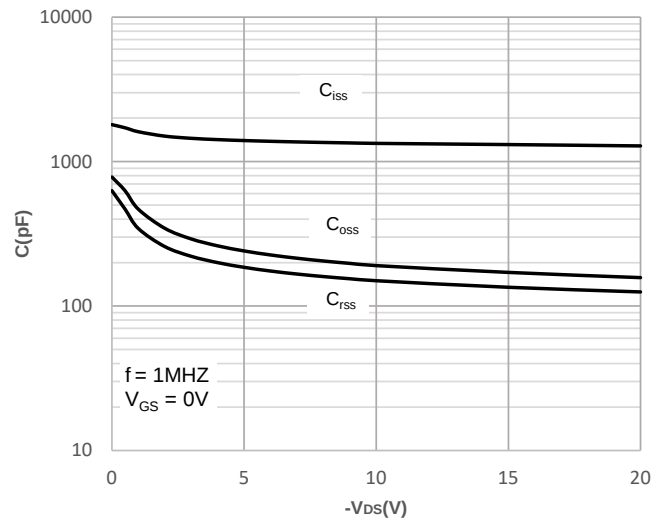


Figure 6: Capacitance Characteristics



Typical Performance Characteristics

Figure 7: Normalized Breakdown voltage vs. Junction Temperature

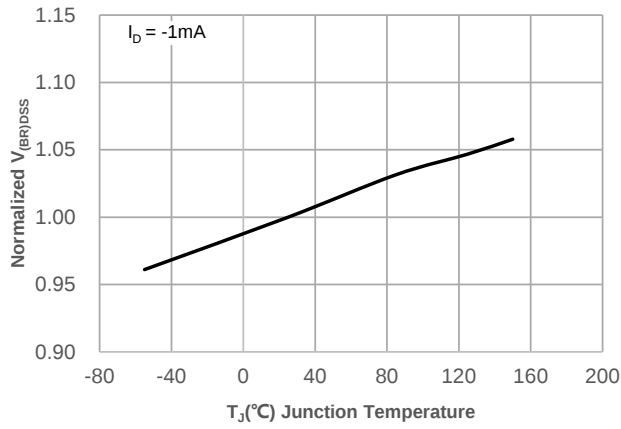


Figure 8: Normalized on Resistance vs. Junction Temperature

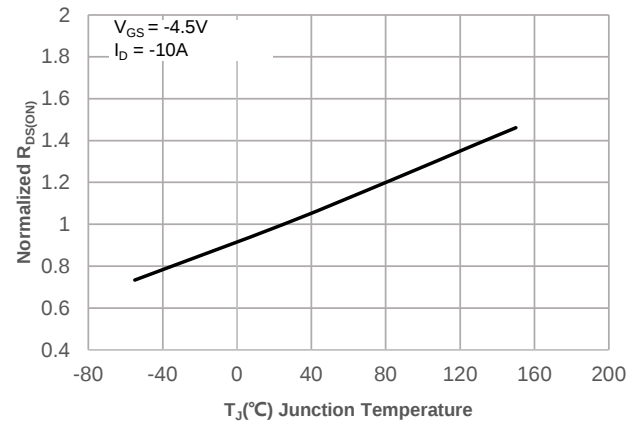


Figure 9: Maximum Safe Operating Area

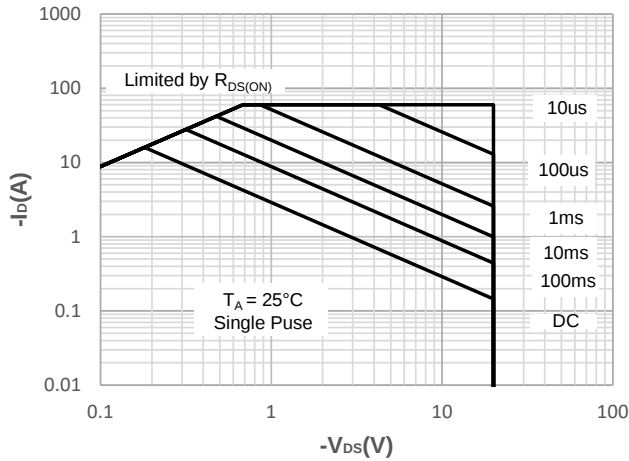


Figure 10: Maximum Continuous Driand Current vs. Ambient Temperature

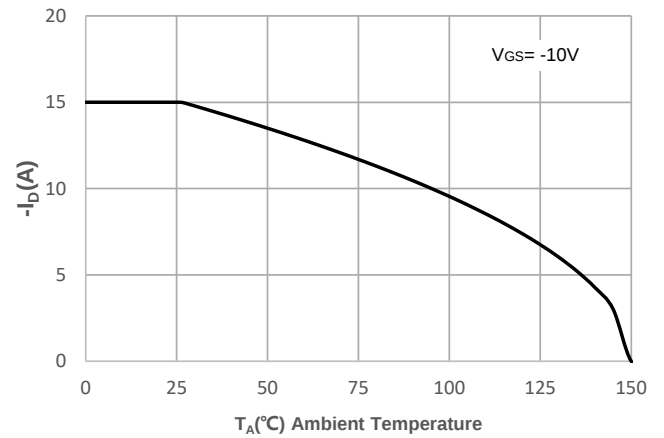


Figure 11: Normalized Maximum Transient Thermal Impedance

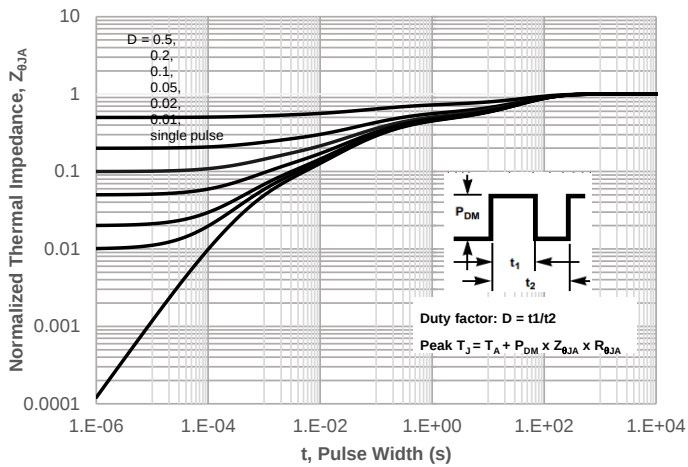
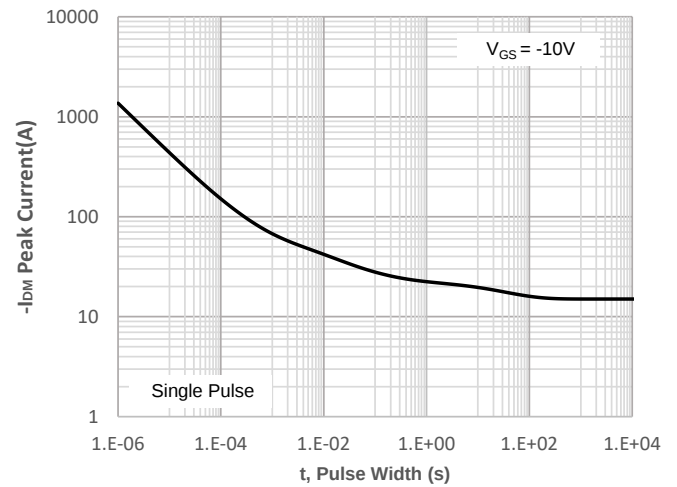


Figure 12: Peak Current Capacity



Test Circuit

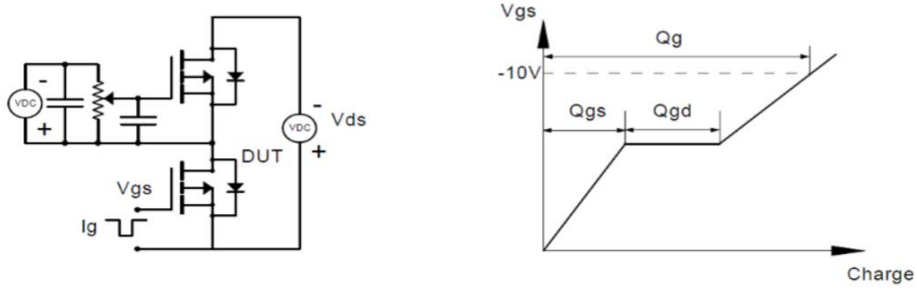


Figure 1: Gate Charge Test Circuit & Waveform

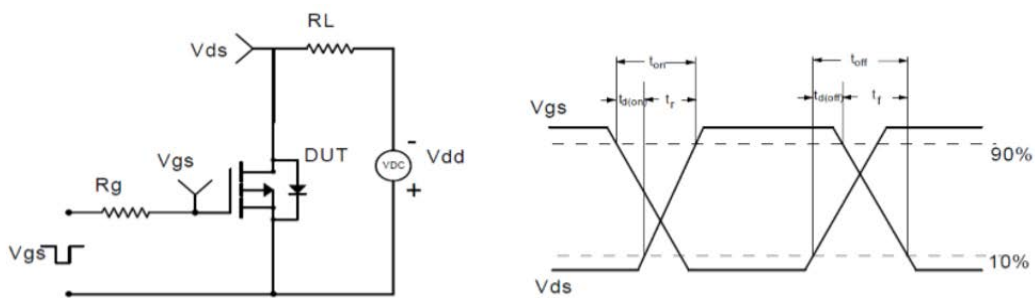


Figure 2: Resistive Switching Test Circuit & Waveform

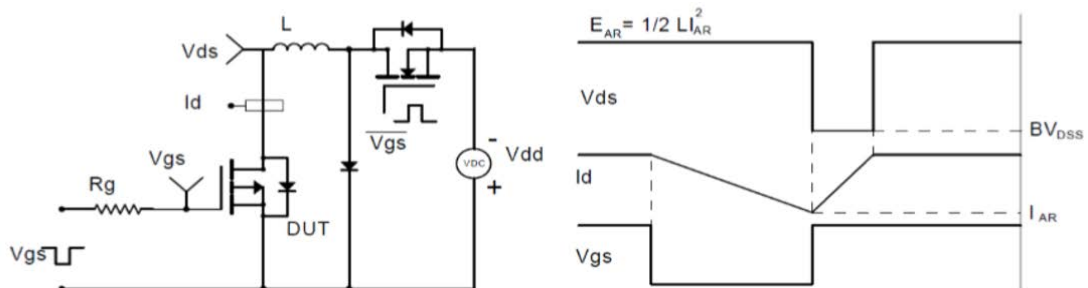


Figure 3: Unclamped Inductive Switching Test Circuit & Waveform

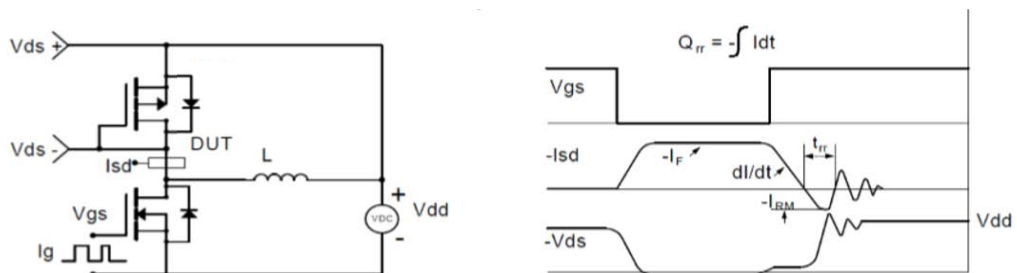
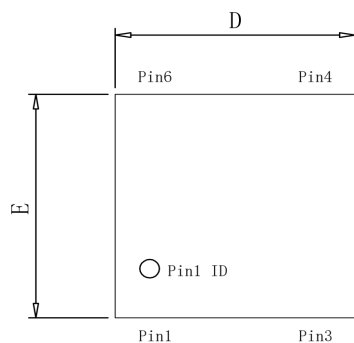
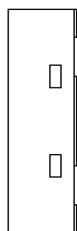


Figure 4: Diode Recovery Test Circuit & Waveform

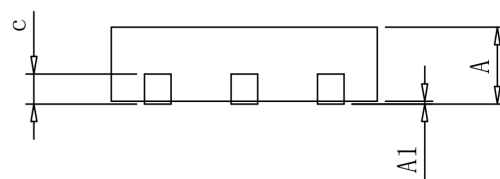
Package Mechanical Data(DFN2020-6L)



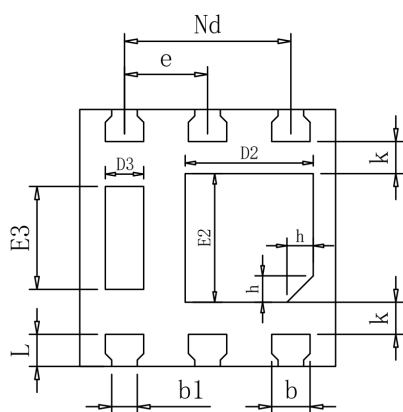
Top View



Side View



Side View



Bottom View

SYMBOL	MILLIMETER		
	MIN	NOM	MAX
A	0.50	0.55	0.60
A1	--	0.02	0.05
b	0.25	0.30	0.35
b1	0.15	0.20	0.25
c	0.203 REF		
D	1.90	2.00	2.10
D2	0.90	1.00	1.10
D3	0.20	0.30	0.40
Nd	1.30 BSC		
e	0.65 BSC		
E	1.90	2.00	2.10
E2	0.90	1.00	1.10
E3	0.70	0.80	0.90
h	0.155	0.205	0.255
k	0.20	0.25	0.30
L	0.20	0.25	0.30